

## Special Issue

# Advancements in Low-Dimensional Materials: Focus on Detailed Methodologies

### Message from the Guest Editors

Low-dimensional materials exhibit a wide range of new properties that can be employed to fabricate improved and novel devices. The ongoing research on these materials is advancing electronics, materials science, and related fields. We would like you to consider submitting a manuscript in this field that provides detailed and rigorous methodologies or processes, as these are crucial for advancing the field and ensuring replicability and robustness in research findings.

### Guest Editors

Dr. Sake Wang

Dr. Nguyen Tuan Hung

Dr. Minglei Sun

### Deadline for manuscript submissions

25 September 2025



## Processes

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*Processes*  
Editorial Office  
MDPI, Grosspeteranlage 5  
4052 Basel, Switzerland  
Tel: +41 61 683 77 34  
[processes@mdpi.com](mailto:processes@mdpi.com)

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### Editor-in-Chief

Prof. Dr. Giancarlo Cravotto

Department of Drug Science and Technology, University of Turin, Via P. Giuria 9, 10125 Turin, Italy

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